External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.20027	100.0	4.20829
			Subtotal	0.20027	100	4.20829
Die	Doped silicon	Silicon (Si)	7440-21-3	0.36645	100.0	7.7
			Subtotal	0.36645	100	7.7
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.03341	10.0	0.702
	Silver alloy	Silver (Ag)	7440-22-4	0.00668	2.0	0.1404
	Lead alloy	Lead (Pb)	7439-92-1	0.294	88.0	6.1776
			Subtotal	0.33409	100	7.02
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.0654	100.0	1.37413
			Subtotal	0.0654	100	1.37413
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00699	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00466	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00699	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.02564	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	23.26507	99.81	488.8594
			Subtotal	23.30935	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.2459	100.0	5.167
			Subtotal	0.2459	100	5.167
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	2.26436	3.0	47.58
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.52871	6.0	95.16
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	7.54785	10.0	158.6
	Carbon Black	Carbon black	1333-86-4	0.37739	0.5	7.93
	Filler	Misc. Silica compounds (generic)	14808-60-7	58.87326	78.0	1237.08
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	1.88696	2.5	39.65
			Subtotal	75.47853	100	1586
			Total	99.99999	100	2101.25943

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.